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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: THREE-DIMENSIONAL STACKED SEMICONDUCTOR
PACKAGE DEVICE WITH BENT AND FLAT LEADS AND
METHOD OF MAKING SAME
Serial No.: 10/695,564 Filed: October 28, 2003
Examiner: Williams, A. Group Art Unit: 2826
Atty. Docket No.: BDG005-6

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

STATUS INQUIRY

Applicant has not received an action for the captioned-application after the Response filed on September 13, 2004. Accordingly, Applicant requests information on the status of the captioned-application.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 22, 2006.

D. Sigmond

David M. Sigmond
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6/22/06

Date of Signature

Respectfully submitted,

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